

## ET-063-10-13

Thot=27 °C (300 °K)					Dimensions (mm)			
I <sub>max</sub> (A)	U <sub>max</sub> (V)	Q <sub>max</sub> (W)	dT <sub>max</sub> (K)	R <sub>ac</sub> , Ohm	A	B	H	D
3.9	7.8	19	74	1.8	30	15	3.6	n/a
Note 1	Note 2	Note 3	Note 4	Note 5				

Note 1 - Maximum current at  $\Delta T_{max}$

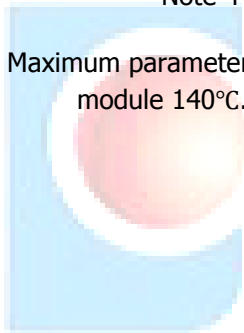
Note 2 - Maximum voltage at  $\Delta T_{max}$

Note 3 - Maximum cooling capacity at I<sub>max</sub>., V<sub>max</sub>. and  $\Delta T=0^{\circ}C$

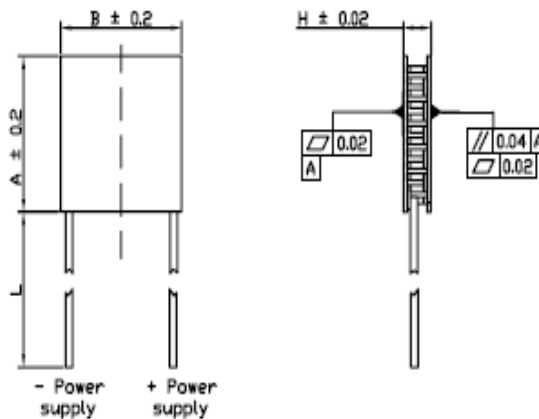
Note 4 - Maximum temperature difference at I<sub>max</sub>., V<sub>max</sub>. and Q=0W

Note 5 - Measured by AC 4-terminal method at 25°C

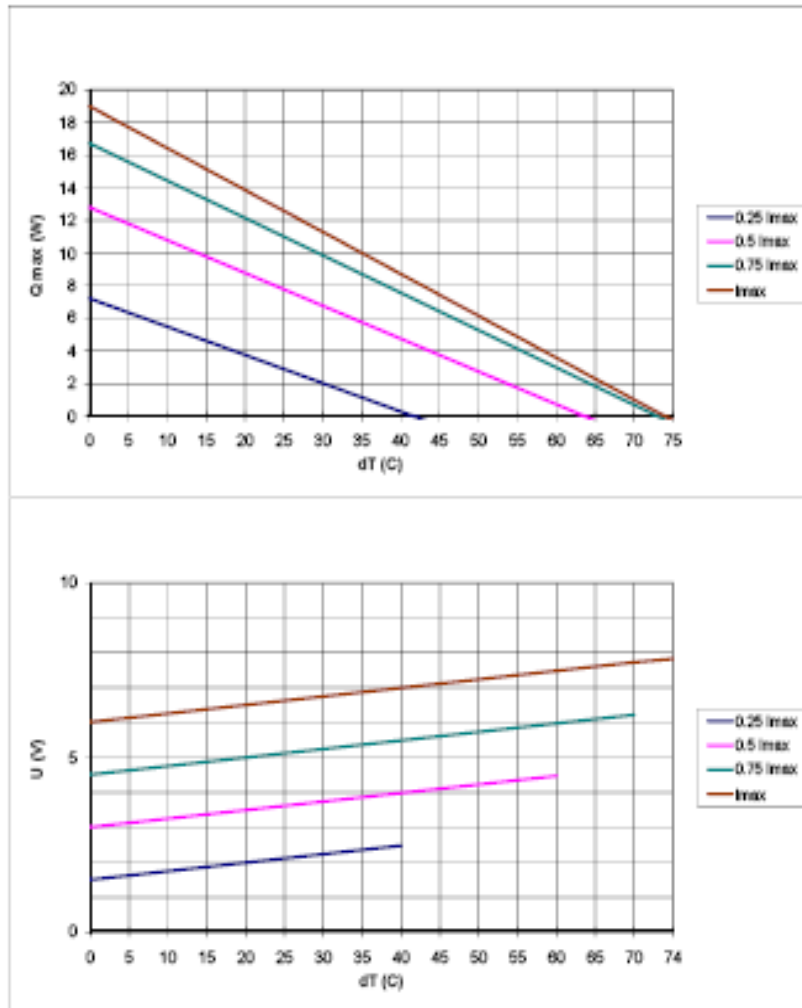
Maximum parameters are measured in a vacuum 1.3P. The solder melting point of thermoelectric module 140°C. Recommended maximum compression (not destruction limit) 1000Kpa



Global Component Sourcing



Max  $dT$  is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



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**Recommendations:**

- Maximum temperature for short periods: 110 °C
- Maximum continuous operation temperature up to 90 °C
- High reliability in ON-OFF mode
- Recommended current not higher than 0.7 of  $I_{max}$